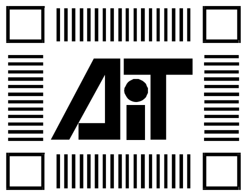

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PRIMA-BOND

EG7655-LV1

Lower Viscosity Paste
Flexible Epoxy Adhesive
Thermally Conductive
Stress-Free Bonding
2-Component, Premixed Frozen

IDEAL FOR:

- Substrate Attach
- Heat-Sink Attach
- Component Attach
- Large Area Bonding
- Bonding Adherends with Mismatched CTE's

DESCRIPTION:

EG7655-LV is a reworkable, alumina filled, electrically insulating, and thermally conductive epoxy paste adhesive. It exhibits outstanding flexibility for bonding materials with highly mismatched CTE's (i.e., alumina to aluminum, silicon to copper). This low viscosity version of EG7655 has high thermal conductivity and flexibility making it excellent for bonding large area substrates, components and heat sinks where thermal management is critical.

EG7655-LV is reworkable at 80-100ºC.

TYPICAL PROPERTIES*

Property	Value
Electrical Resistivity (150 ºC/ 60 minutes)	>1x10 ^{14} ohm-cm
Dielectric Strength (Volts/mil)	> 750
Glass Transition Temp.(ºC)	-25 ±10%
Current Carrying Capabilities	N/A
Lap-Shear Strength	>800 psi >5.5 N/mm²
Device Push-off Strength	>1500 psi >10.3 N/mm²
Cured Density (gm/cc)	2.3 ±10%
Thermal Conductivity	12 Btu-in/hr-ft²-ºF ±10% 1.7 W/m-ºC ±10%
Linear Thermal Expansion Coeff. (ppm/ºC)	120
Maximum Continuous Operation Temp. (ºC)	<150
Avg. Viscosity(0.5 rpm, 24ºC) (Brookfield DV-1, spindle CP51)	70,000 cp ±20%

* Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is intended to be used in manufacturing and in the final product.

AVAILABILITY:

EG7655-LV1 is available in syringes for automatic needle dispense applications or in jars. Both viscosity and thixotropic index can be modified to your specific needs. The material can be shipped premixed and frozen upon request.

APPLICATION PROCEDURES:

(1) Store Part A and Part B at ambient.

(2) Mix A and B 1:1 by weight.

(3) Cure according to one of the recommended schedules.

CURE SCHEDULES:

Temperature	Time
85ºC	4 hr
100ºC	2 hr
125ºC	1 hr
150ºC	30 min

If the material is premixed and frozen thaw for 30 minutes, apply and cure according to one of the recommended schedules.

**Shelf life is for unmixed components. If premixed:-40ºC for 6 months. Pot life is 8 hours at 25ºC, after mixing.

SHELF LIFE:

Storage temperature	Shelf Life
**25ºC	1 yr

CAUTION: This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer SDS for more details.

The information contained herein is believed to be reliable. All recommendations or suggestions are made without guarantee inasmuch as conditions and methods of commercial use are beyond our control. Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is to be used in manufacturing and in the final product. Under no circumstance shall AI Technology be liable for accidental, consequential or other damages arising from the use or handling of this product.

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